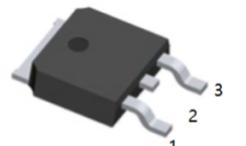


## Features

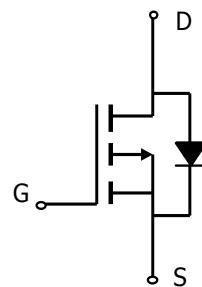
- $V_{DS}$  (V) = -40V
- $I_D$  = -40A
- $R_{DS(ON)} < 22m\Omega$  ( $V_{GS} = -10V$ )
- $R_{DS(ON)} < 29m\Omega$  ( $V_{GS} = -4.5V$ )



1.G 2.D 3.S  
TO-252(DPAK) top view

## General Description

The AOD4189 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. With the excellent thermal resistance of the TO-252 package, this device is well suited for high current load applications.



## Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>B,H</sup>	$I_D$	-40	A
$T_C=100^\circ C$		-28	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	-50	
Avalanche Current <sup>C</sup>	$I_{AR}$	-35	
Repetitive avalanche energy $L=0.1mH$ <sup>C</sup>	$E_{AR}$	61	mJ
Power Dissipation <sup>B</sup>	$P_D$	62.5	W
$T_C=100^\circ C$		31	
Power Dissipation <sup>A</sup>	$P_{DSM}$	2.5	
$T_A=70^\circ C$		1.6	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175	°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A,G</sup>	$R_{\theta JA}$	15	20	°C/W
Steady-State		41	50	°C/W
Maximum Junction-to-Case <sup>D,F</sup>	$R_{\theta JC}$	2	2.4	°C/W

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-40			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=-40\text{V}, V_{GS}=0\text{V}$			-1	$\mu\text{A}$
			$T_J=55^\circ\text{C}$		-5	
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			$\pm 100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.7	-1.9	-3	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=-10\text{V}, V_{DS}=-5\text{V}$	-50			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-12\text{A}$		18	22	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-8\text{A}$		23	29	
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-12\text{A}$		35		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.74	-1	V
$I_S$	Maximum Body-Diode Continuous Current				-20	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-20\text{V}, f=1\text{MHz}$		1870		pF
$C_{\text{oss}}$	Output Capacitance			185		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			155		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	2.5	4.5	6.5	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(-10\text{V})$	Total Gate Charge	$V_{GS}=-10\text{V}, V_{DS}=-20\text{V}, I_D=-12\text{A}$		31.4	41	nC
$Q_g(-4.5\text{V})$	Total Gate Charge			7.9	10	
$Q_{gs}$	Gate Source Charge			7.6		nC
$Q_{gd}$	Gate Drain Charge			6.2		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=-10\text{V}, V_{DS}=-20\text{V}, R_L=1.6\Omega, R_{\text{GEN}}=3\Omega$		10		ns
$t_r$	Turn-On Rise Time			18		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			38		ns
$t_f$	Turn-Off Fall Time			24		ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=-12\text{A}, dI/dt=100\text{A}/\mu\text{s}$		32	42	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=-12\text{A}, dI/dt=100\text{A}/\mu\text{s}$		30		nC

A: The value of  $R_{\theta JA}$  is measured with the device in a still air environment with  $T_A=25^\circ\text{C}$ . The power dissipation  $P_{\text{DSM}}$  and current rating  $I_{\text{DSM}}$  are based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using steady state junction-to-ambient thermal resistance.

B. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=175^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=175^\circ\text{C}$ .

D. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to case  $R_{\theta JC}$  and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using  $t \leq 300 \mu\text{s}$  pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=175^\circ\text{C}$ . The SOA curve provides a single pulse rating.

G. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ .

H. The maximum current rating is limited by bond-wires.

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**P-Channel MOSFET**

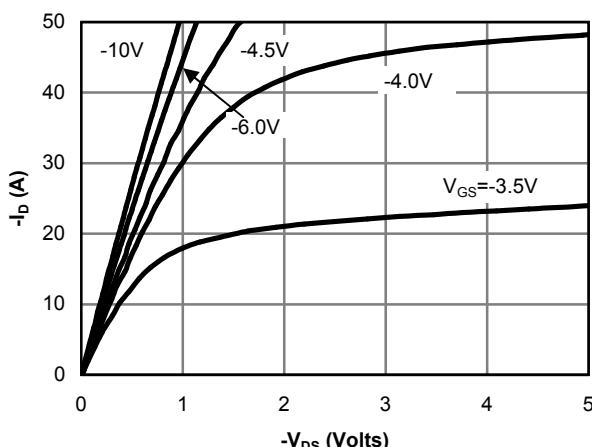


Figure 1: On-Region Characteristics

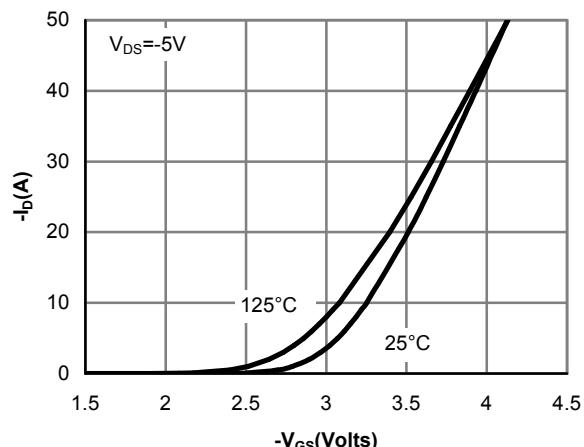


Figure 2: Transfer Characteristics

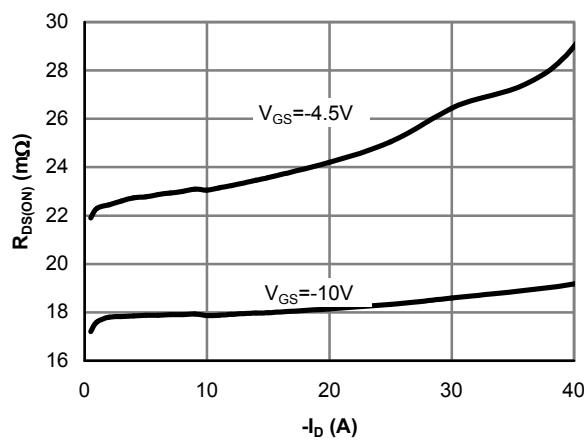


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

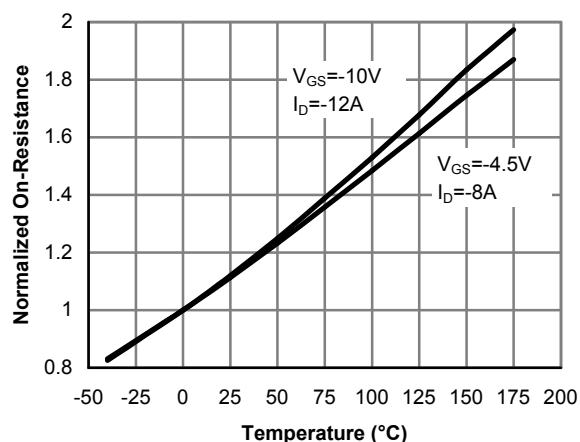


Figure 4: On-Resistance vs. Junction Temperature

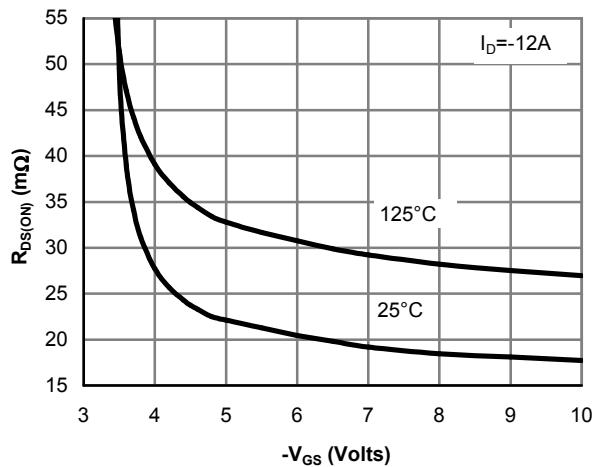


Figure 5: On-Resistance vs. Gate-Source Voltage

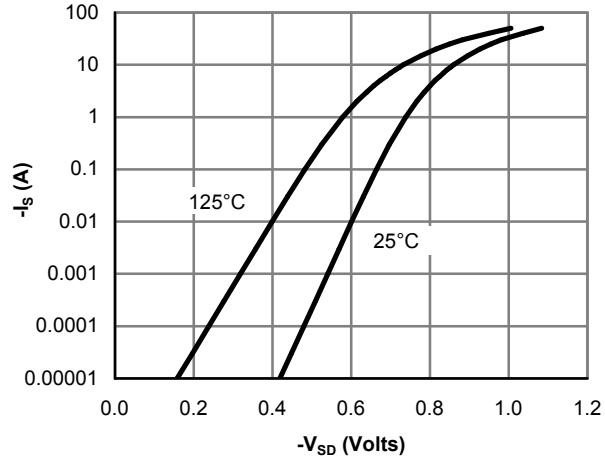


Figure 6: Body-Diode Characteristics

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

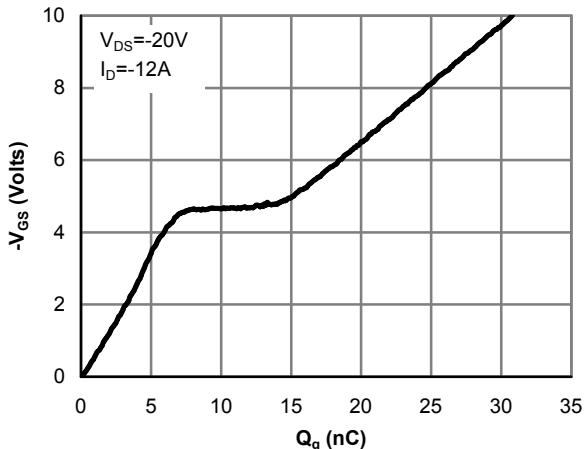


Figure 7: Gate-Charge Characteristics

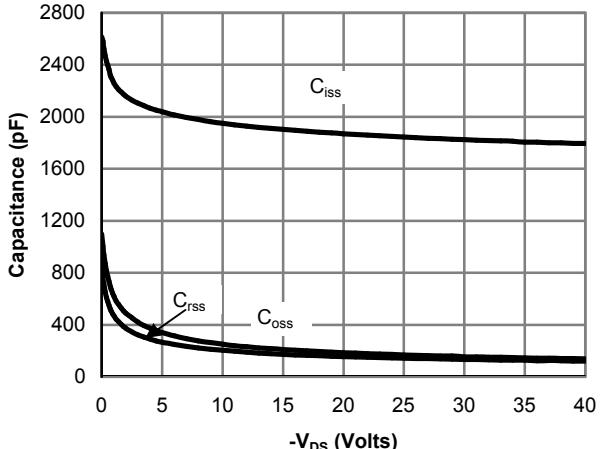


Figure 8: Capacitance Characteristics

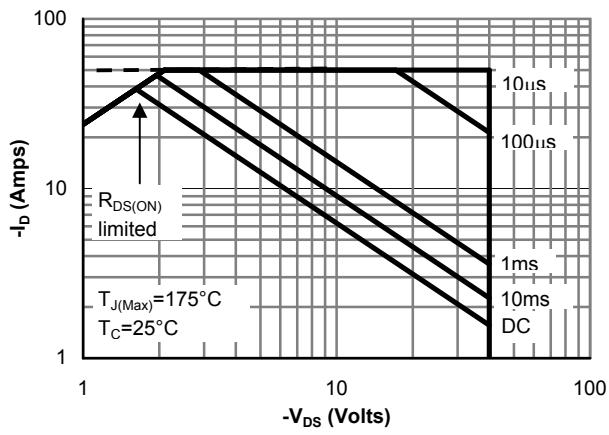


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

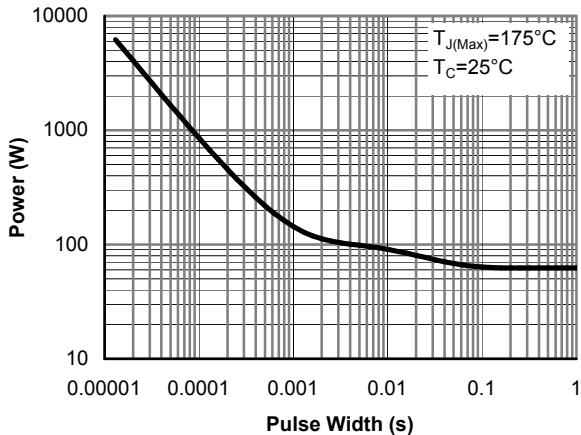


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

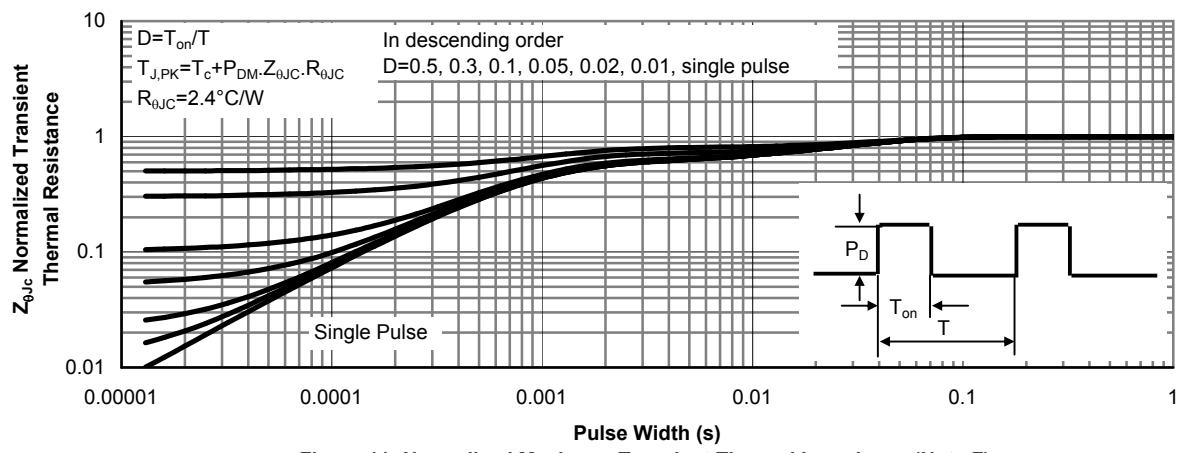


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

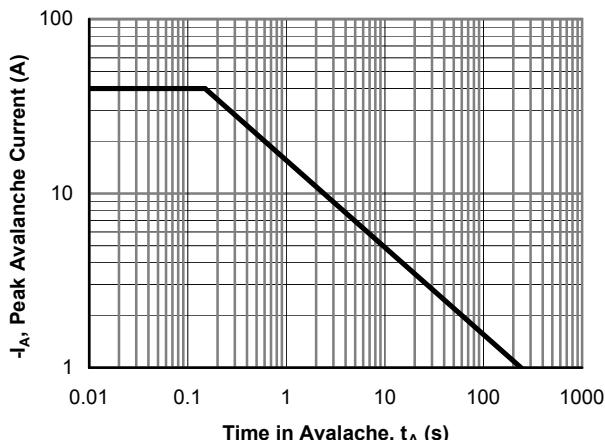


Figure 12: Single Pulse Avalanche Capability

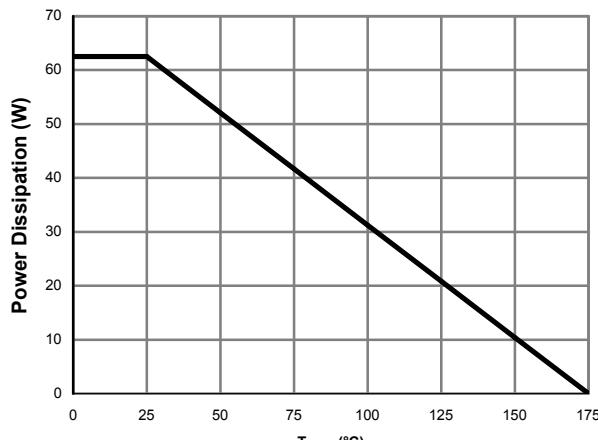


Figure 13: Power De-rating (Note B)

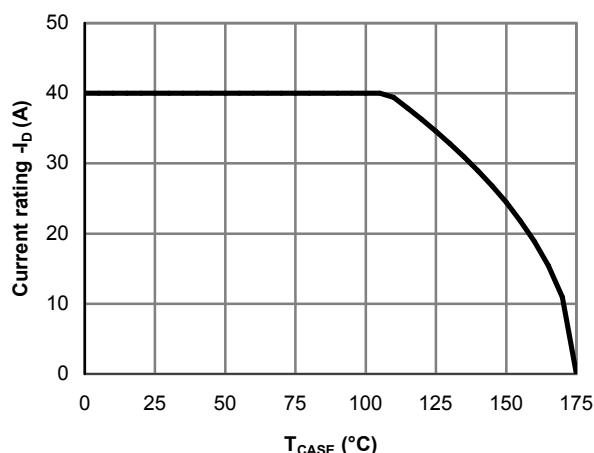


Figure 14: Current De-rating (Note B)

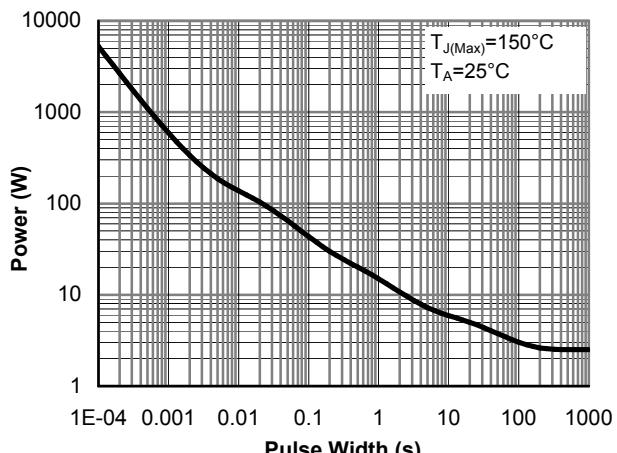


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note G)

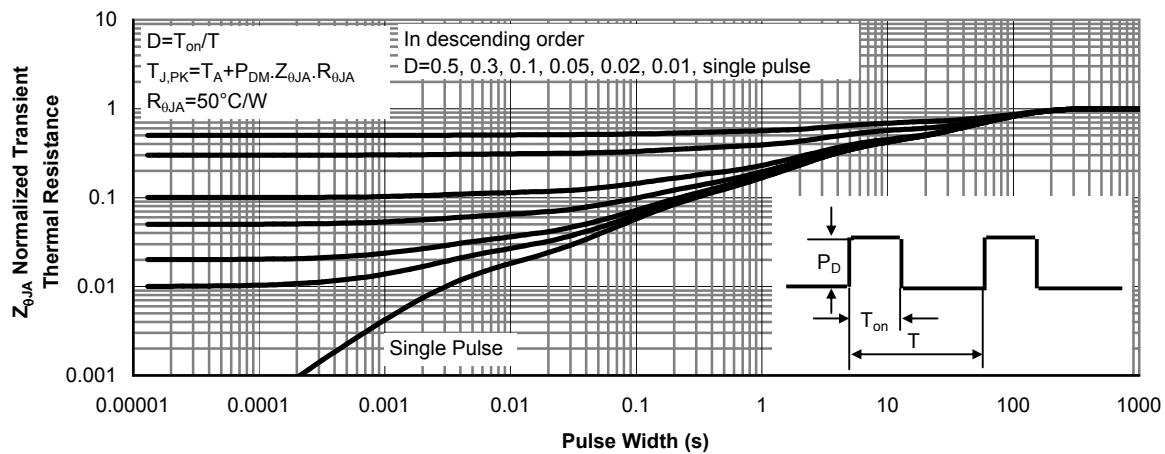
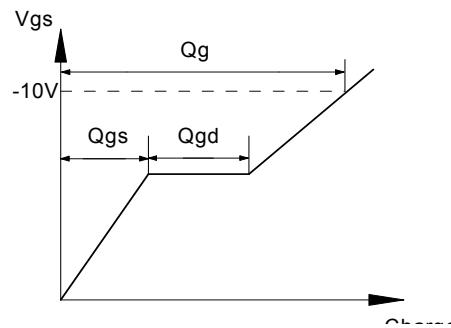
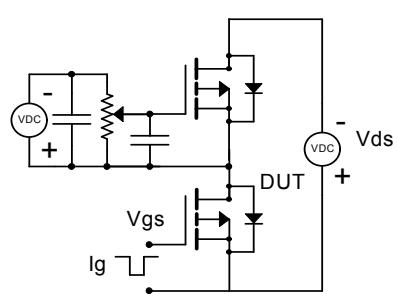
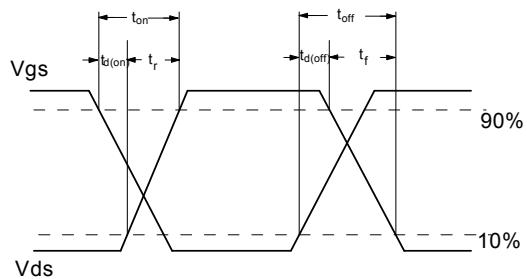
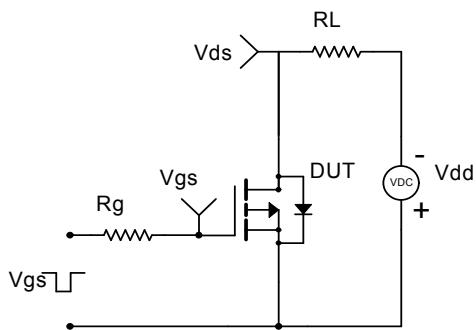


Figure 16: Normalized Maximum Transient Thermal Impedance (Note G)

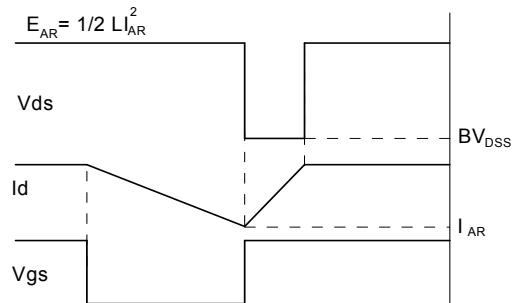
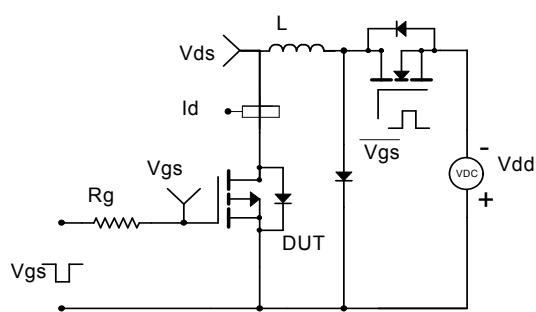
Gate Charge Test Circuit & Waveform



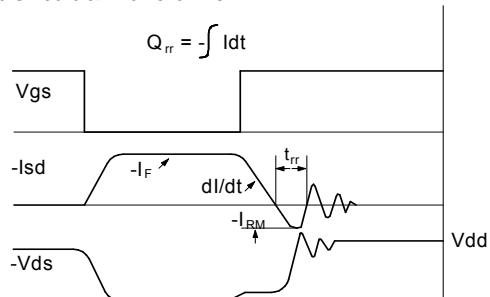
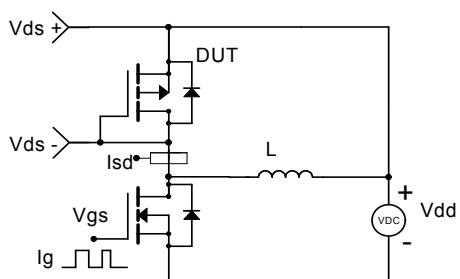
Resistive Switching Test Circuit & Waveforms



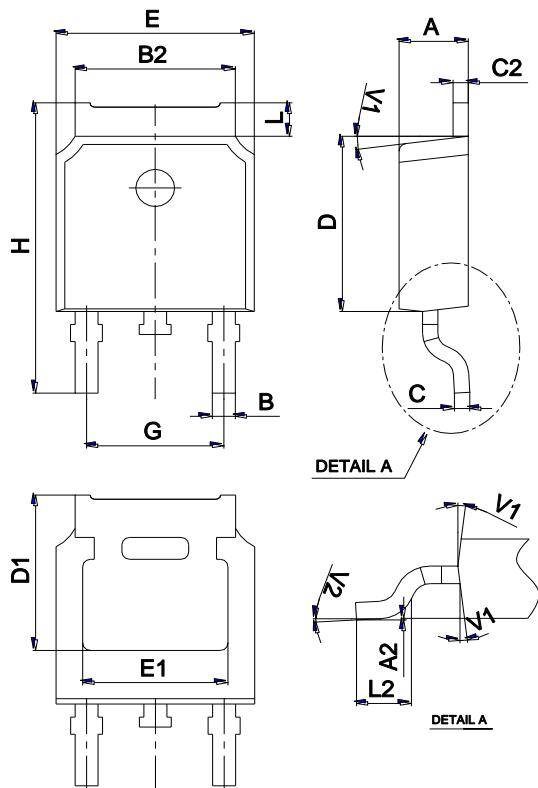
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

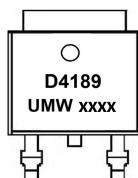


## Package Mechanical Data TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

## Marking



## Ordering information

Order code	Package	Baseqty	Deliverymode
UMW AOD4189	TO-252	2500	Tape and reel